Application solutions

HDMI Connectors

Electronics / Connectors

Benefits

• PA4T good flow (> PPA, = LCP) PA4T low moisture absorption

Details

For Tii® PA4T allows for reliable solutions due to its high melting temperature (ideal for reflow process), high mechanical performance (also after reflow soldering), a high dimensional stability (result from low, isotropic CLTE), a high co-planarity and low warpage after soldering, and good dielectrics due to low moisture uptake; ForTii® PA4T allow for cost effective solutions to due good processability and high flowability enabling thin walled designs; ForTii® PA4T allow for even more sustainable solutions with reduced environmental impact due to its lower carbon footprint as compared to alternative materials

Products

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Typical values are indicative only and are not to be construed as being binding specifications. Colorants in the product or other additives may cause significant variations in typical



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